

Technical Information

Polymer OH

Hydroxy-terminated polydimethylsiloxan

Polymer OH are polydimethyl siloxanes with terminal silanol groups used as base polymers in condensation-curing silicone elastomers. Polymer OH is available in different viscosity levels between 100 and 400 000 mPas. Other viscosities are available upon request. Please note that Polymer OH 0.1 acts as an inhibitor and can therefore be used for delaying the curing process.

Technical data (no specification)

Product name	Viscosity at 25 °C [mPas]	Product name	Viscosity at 25 °C [mPas]
Polymer OH 0.1	100	Polymer OH 5	5 000
Polymer OH 1	1 000	Polymer OH 20	20 000
Polymer OH 2	2 000	Polymer OH 80	80 000
Polymer OH 3.5	3 500	Polymer OH 300	400 000

Technical data (no specification)

Property	Unit	
Appearance		clear, colourless liquid
Refractive index n_D^{20}		1.4058
Density (20 °C)	[g/cm ³]	0.98

Application

Polymer OH can be cured with usual condensation cross-linkers such as alkoxy silanes, acetoxy silanes, oxime silanes (Crosslinker OX) and enoxy silanes in connection with catalysts (e. g. tin catalysts, Catalyst TD 18).

Especially the low-viscosity types can be used as reactive diluents for the viscosity adjustment in a mixture with higher viscosity polymers.

The crosslinking reaction occurs in connection with water. In conventional single-component formulations, this water can be introduced through humidity. However, Polymer OH can also be formulated as two component systems. In that case, the required water is added through the second component. Substantially higher curing rates and depths are achieved in this way.

Packaging and Storage

Packaging	950 kg IBC PE, different packaging upon request
Shelf life	24 months in originally sealed containers
Storage	Dry, up to 30 °C (86 °F) in sealed containers

Safety and Handling

The rules and regulations for the handling and use of chemicals have to be observed. Please refer to the Material Safety Data Sheet for further details.

Registration status

The ingredients of all mentioned Polymer OH products are listed in the following chemical inventories:

EINECS/ELINCS, TSCA, DSL, ENCS, AICS, TCCL, PICCS, IECSC, New Zealand, TCSI

Further information is available on request.

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